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3-6-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

A. K. Sarkhel et al.

Serial No: N/A

Filed: Herewitch 1-26-0

Title: LEAD-FREE HIGH TIN TERNARY
SOLDER ALLOY OF TIN,
SILVER, AND BISMUTH

Group Art Unit: N/A

1742

Examiner: N/A ID

Docket No. EN995038US5

IBM Corporation
Intellectual Property Law
Department N50/040-4
1701 North Street
Endicott, NY 13760

PRELIMINARY AMENDMENT

Honorable Commissioner of Patents and Trademarks
Washington, DC 20231

Dear Sir:

Prior to initial examination on the merits, please amend the
above-identified application as follows:

IN THE SPECIFICATION

On page 1, line 4, delete "The present invention" and add
-- This application is a divisional application of serial no.
09/216,042 which --.

IN THE CLAIMS

Please cancel claim 1-7, 11, and 12.

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